Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	336986	(substrate carruer board pcb ((printed wiring circuit) adj4 board)) with (via hole hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 01:50
L2	3432858	(die chip ic (integrated adj circuit) semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 01:47
L3	4299	1 same 2 same wire same (bond finger pad eleectrode trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 01:48
L4	5818	1 same 2 same wire same (bond bonding finger pad eleectrode trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 01:51
L5	1055	4 same ((ground same power) (input output)(o i))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 01:50
L6	1560	4 same ((ground power) (input output)(o i))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 01:51
L7	430008	(substrate carrier board pcb ((printed wiring circuit) adj4 board)) with (via hole hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 01:50
L8	7167	7 same 2 same wire same (bond bonding finger pad electrode trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 01:51

| L9 | 1932 | 8 same ((ground power) (input output)(o i)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/10 01:52 |
| L10 | 281 | dc and 9 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/10 01:52 |